

# Precision SMT pick & place machine - P1 with optical alignment system



## • TECHNICAL DATA

- **PCB**
  - max. placement area 400 x 500mm
- **Components range**
  - from 0201 up to 30x30mm
  - Pitch min. 0,4mm
- **Components packing**
  - tapes / sticks / trays / bulk
- **Components centering**
  - non-contact alignment
- **Placement rate**
  - up to 600 cph
- **Feeder capacity**
  - up to 80 x 8mm – strips feeder and
  - 2 x (300 x 200mm) - IC-tray with 200 x 300mm PCB size
- **Resolution**
  - X / Y Axis – 0,008mm ( linear encoders )
  - Z Axis – 0,020mm ( linear encoder )
  - Rotation – 0,01° ( rotation encoder )
- **Placement accuracy**
  - +/- 0,03 mm
- **Dimensions and weight**
  - 840 x 630 x 430 mm / ca. 75 kg
- **Supply**
  - 230 V - 50 Hz - 450 W / 0,6 Mpa -15 l/min

## • KEY FEATURES

- precision automatic SMT pick and place machine with optical alignment system
- automatic pick & place head
- automatic nozzle changer (6 tools )
- camerasystem for automatic fiducial
- camerasystem for touchless components centering
- CAD – editor for pick & place files ( all CAD´s )
- vision inspektion of printing accuracy of solder paste and accuracy of component placement
- remote service via internet
- control panel: PC keyboard / Mouse
- Graphical user interface
- **Application range**
  - prototypes and low volume production
  - pick & place of standard and fine pitch components incl. SOIC, PLCC, BGA ,  $\mu$ BGA, CSP, QFN, LED´s